

# Advanced Solution for Vertical-in-Line Equipment

# 先进垂直连续酸性电镀铜技术

## COPPER GLEAM™ HV-101 and HV-606 Electrolytic Copper

HV-101 exhibits excellent plating performance and advantage for production. High plating efficiency helps to increase productivity and reduce plating cost. HV-606 is developed from the basis of HV-101 for insoluble anode plating system, which provides similar performance but higher operation current density.

HV-101具备优越的电镀特性与量产的优势。高电镀效率有助于提高产能并减少电镀成本。HV-606为基于HV-101的基础所发展出来的产品，以应用于搭配不溶性阳极的电镀系统。可提供相类似于HV-101的优越表现，且可用于较高的电流密度下。

### Features and Benefits

#### 特性及优点

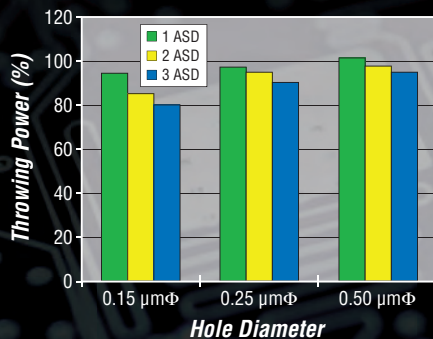
- Excellent throwing power on through hole and microvia over high current density  
在高电流下仍具备优越的通孔与盲孔贯孔能力
- Superior panel plating distribution  
良好的电镀均匀度
- Superior leveling performance for panel surface and rough through hole  
于表面与孔内有良好的整平效果
- Round bottom phenomenon on microvia  
于盲孔底部有圆孔效果
- Good thermal reliability  
优异的耐热信赖度



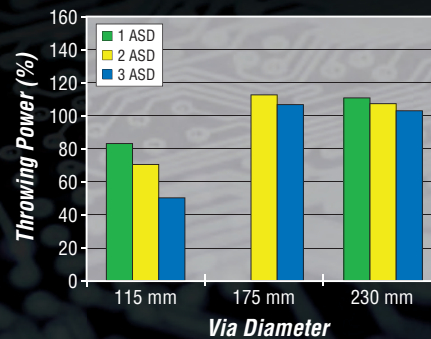
1.6 mm thickness, 0.3 mm diameter



100 μm depth, 150 μm width



TP performance on different through hole diameter and current density (Board Thickness: 1 mm)



TP performance on different microvia diameter and current density (Via Depth: 100 μm)



Electronic Materials